

2021-22

25-11

सदरचा मुद्रांक लिहू अँड लायसेन्ससाठी नाही.



भारत MAHARASHTRA

2020

YT 628052

अनुक्रमांक E292 दिनांक 20/10/2021 रुपये 100
 मुद्रांक कोणत्या कारणासाठी वापरण्याचा आहे करार
 मुंबई मुद्रांक अधिनियम १९५८ चे अनुच्छेद क्र. _____
 मुद्रांक वापरनाराचे संपूर्ण नांव शाचार्य तुळजाराम चतुर्चंद
 संपूर्ण पत्ता कॉलेज, बारामती.
 हस्ते व्यक्तीचे नांव जगदीश देशपांडे.
 पत्ता बारामती

सौ.एस.एम.तांबडे, मुद्रांक विक्रेती
 परवाना क्र.२२०३०२१/२०२४ पर्यंत नुतनीकृत
 विक्री-आनंदनगर, बारामती, जि.पुणे

मुद्रांक धारकाची/हस्ते व्यक्तीची राहणी



Place: Baramati

Date: 29 October 2021

Memorandum of Understanding for Collaboration

[2021-2022]

between

Department of Electronics

Tuljaram Chaturchand College of Arts, Science and Commerce, Baramati

And

Future Chip Technologies, Pune



Signature [Signature]
 Mr. Ramakant Bhujbal
 CEO
 Future Chip Technologies, Pune

Signature [Signature]
 Dr. J. D. Deshpande
 Head
 Department of Electronics

Signature [Signature]
 Dr. Chandrashekhar Murumkar
 Principal
 Tuljaram Chaturchand College,
 Baramati

Memorandum of Understanding for Collaboration

1. AGREEMENT

- 1.1. This agreement made and entered into on the 21 October 2021 between **Department of Electronics, Tuljaram Chaturchand (TC) College Baramati, Maharashtra** established on 27/04/1962 in pursuance of the Bombay Public Trust Act-1950 and having its headquarters at Baramati, (herein after called TC which expression shall where the context so admits includes it's successor and permitted assigns)
- 1.2. **Future Chip Technologies**, having its registered office at Pune Dist. Pune of the other part.

2. BACKGROUND

- 2.1. Whereas the TC has the supporting facilities, human resources in terms of faculties and students desirous of undertaking teaching, research, development, and extension programmes in the disciplines of Physics is desirous of undertaking collaborative work with Future Chip Technologies and provide facilities and resources for industrial training.
- 2.2. Whereas Future Chip Technologies has the expertise in the Electronics Parts and devices in the field of laboratories, and automation.
- 2.3. Faculties from TC and engineers from Future Chip Technologies had meetings to discuss the common collaborative work to benefit the students and society complementing each other's work. Consequently, it was decided to have a MoU as a tool to facilitate joint efforts to achieve objectives of mutual interests of TC and Future Chip Technologies.

Now therefore in consideration of premises and mutual covenants herein after content, the TC and Future Chip Technologies hereby agree as follows:

3. SCOPE OF THE AGREEMENT

- 3.1. TC and Future Chip Technologies may offer opportunities to the other for activities and programs, such as guest lecture, training of students and industrial visits that will foster a collaborative relationship.
- 3.2. Specific Activities: Specific activities and programs implemented under the authority of this MoU and as decided from time to time on the topics of mutual interest of Department of Electronics of TC and Future Chip Technologies shall be subject to availability of funds and the approval of each institution's authorized representatives. The institutions contemplate implementation of programs or activities such as:
 - (a) Joint educational and training activities
 - (b) Exchange of expertise, graduate, postgraduate students for lectures, and discussions
 - (c) Exchange of academic materials and other information
 - (d) Special, short-term training programs and
 - (e) Industrial visits for students

Signature-----
Mr. Ramakant Bhujbal

CEO
For FUTURE CHIP TECHNOLOGIES
Future Chip Technologies, Pune

Signature-----
Dr. J. D. Deshpande
Head
Department of Electronics

Signature-----
Dr. Chandrashekhar Murumkar
Principal
Tuljaram Chaturchand College
Baramati

4. STUDENTS TRAINING

- 4.1. The TC and Future Chip Technologies will provide the laboratory expertise for the conduct of undergraduate (UG), postgraduate (PG) training work necessary to enhance skills.
- 4.2. The Future Chip Technologies will not have any financial liability towards the provision of fellowship/scholarship to the students.
- 4.3. The period of work and number of students per discipline shall be decided mutually by TC and Future Chip Technologies.
- 4.4. The Head of TC and the CEO of Future Chip Technologies will settle any differences/policy issues arising out of implementation of this agreement after mutual consultation. Their decision will be final.

5. RESPONSIBILITIES OF TC AND FUTURE CHIP TECHNOLOGIES

- 5.1. TC and Future Chip Technologies shall ensure access to the facilities to be used for project activities to concern students without restrictions on time wherever necessary.
- 5.2. The access to the lab facilities wherever necessary may be facilitated by TEMPORARY ENTRY CARDS that can be used throughout the project period.
- 5.3. TC and Future Chip Technologies shall undertake the work on the collaborative training as per schedule of work mutually agreed by the parties.
- 5.4. TC/ Future Chip Technologies shall provide all the basic facilities, to each other for fulfillment of the training under the agreement.

6. CONFIDENTIALITY

Information as may be vital to the interest of the Institutes/Company, or security/defense of the country is not parted with any other party.

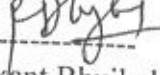
7. FINANCIAL AGREEMENT

As a general principle, funding for the exchange of such personnel shall be based on a reciprocal sharing of costs:

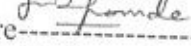
- 7.1 Travelling, accommodation and daily expenses of the participating students/faculties/engineers required for visit/meetings under this agreement will be borne by the respective institute/company as per the prevailing rules and regulations, if such meetings are not sponsored by third party funding agencies.
- 7.2 Each institute will provide assistance and/or the necessary letters of invitation.

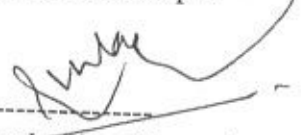
8. MODALITIES OF COLLABORATION

TC and Future Chip Technologies shall jointly identify centers / locations for carrying out studies/activities of any products emerging from collaborative project and draw up protocols for such trials/ studies/ activities. The TC and Future Chip Technologies shall undertake / assist/ co- operate with each other to carry out trials/studies/activities as per the protocols drawn up.

Signature 
Mr. Ramakant Bhujbal

CEO
For FUTURE CHIP TECHNOLOGIES, Pune

Signature 
Dr. J. D. Deshpande
Head
Department of Electronics

Signature 
Dr. Chandrashekhar Murumkar
Principal
Tuljaram Chaturvedi College
Baramati

9. EFFECTIVE DATE, DURATION, TERMINATION OF THE AGREEMENT

- 9.1 The agreement shall be effective from the (date of signing/specify events) and shall recur in force for a period of Three years from said date.
- 9.2 The agreement shall be deemed to expire on completion of the period as in provision unless extended by both the parties.
- 9.3 During the tenure of the agreement parties here to can terminate the agreement either for breach of any of the terms and conditions of this agreement or otherwise by giving a (Three month) notice in writing to the defaulting party, failure of either party to terminate the agreement on account of breach or default by the other shall not constitute a waiver of that party's right to terminate this agreement.
- 9.4 In the event of termination of the agreement the right and the obligations of the parties thereto shall be settled by mutual discussion.

10 AMENDMENT OF THE AGREEMENT

- 10.1 No Amendment or modification of this agreement shall be made unless the same is made in writing by both the parties and their authorized representatives and specifically stating the same to be an amendment of this agreement. The modification/changes shall be effective from the date on which they are made/executed, unless otherwise agreed to
- 10.2 The right and/or liabilities arising to any party to this agreement shall not be assigned except with the written consent of the party and subject to such terms and conditions as may be mutually agreed upon.

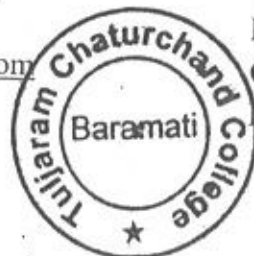
11 USE OF NAME

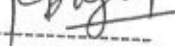
The Parties agree not to use each other's names in any advertising or other form of publicity without the prior written consent of that Party. However, the Parties agree in advance that each may use the name of the other in announcing this MoU.

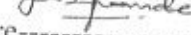
12 ADDRESS FOR THE NOTICES


Department of Electronics
Tuljaram Chaturchand (TC) College,
P.B.No.51, Baramati-413102, Pune,
Phone: 02112-222405, 222728
Email: principal.tccollege@gmail.com
principal@tccollege.org

Future Chip Technologies,
409, Shaniwar Peth, Kakasaheb
Gadgil Road, Near Mandar Lodge,
Pune-411030.
Contact: 9890141705/9890136461
Email: ramakantbhuibal@gmail.com



Signature 
Mr. Ramakant Bhujbal
CEO

Signature 
Dr. J. D. Deshpande
Head
Department of Electronics

Signature 
Dr. Chandrashekhar Murumkar
Principal
Tuljaram Chaturchand College
Baramati

Future Chip Technologies, Pune
For FUTURE CHIP TECHNOLOGIES

13 SEAL OF PARTIES

In witness whereas of the parties hereto have signed this agreement on the day, month and year mentioned hereinbefore.

PARTIES

For and on behalf of TC

Signature J. D. Deshpande
Mr. J. D. Deshpande
Department of Electronics

For and on behalf of Future Chip Technologies

Signature Dr. Chandrashekhar Murumkar
Principal
Tularam Chaturchand College
Baramati
Seal

Signature Mr. Ramakant Bhujbal
CEO
Future Chip Technologies, Pune
Sea For FUTURE CHIP TECHNOLOGIES



PROPRIETOR

Witnesses (Name and Address)

- 1) Dr. A.S. Jagtap (Signature) T.C. College, Baramati.
- 2) Prof V T Yelvale (Signature) " "
- 3) Prof Miss A.M. Pawar (Signature) " "
- 4) Prof. Deepak S. Kumbhar (Signature) Future Chip Technologies, Pune.